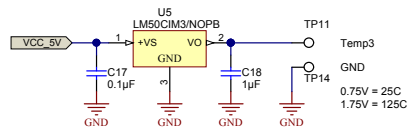
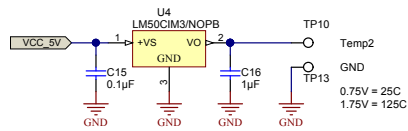
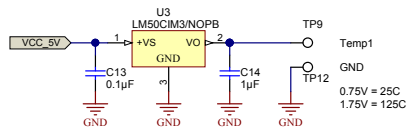
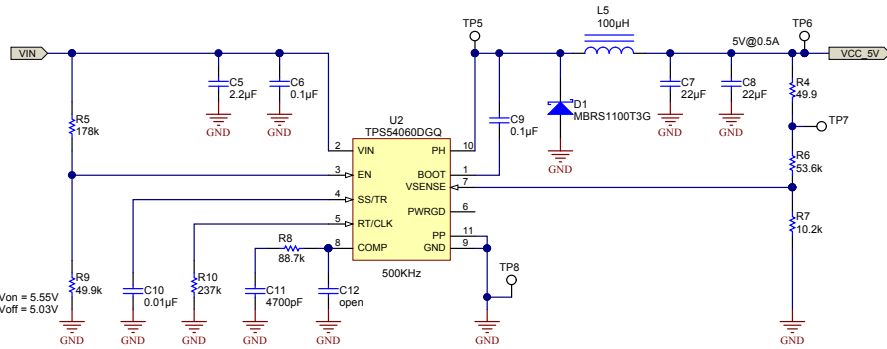
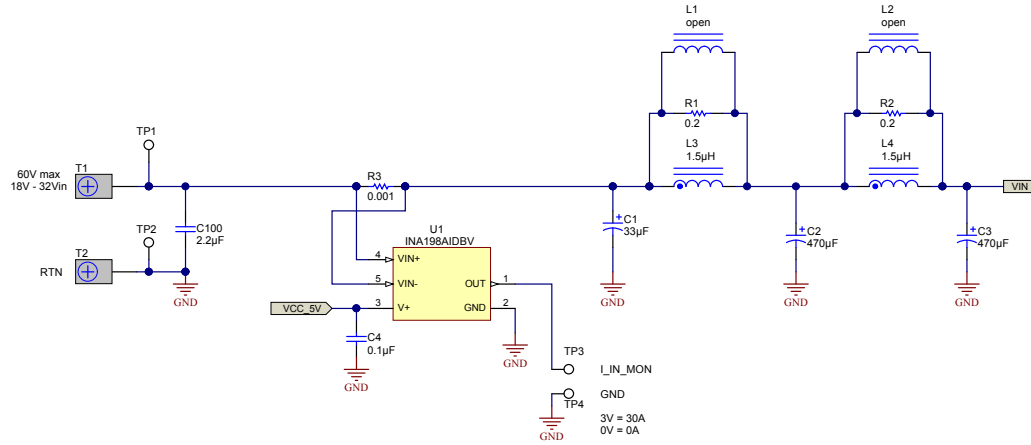


NOTES:
1) REVB changes C45, C47, R38 and adds C100 to PWB.

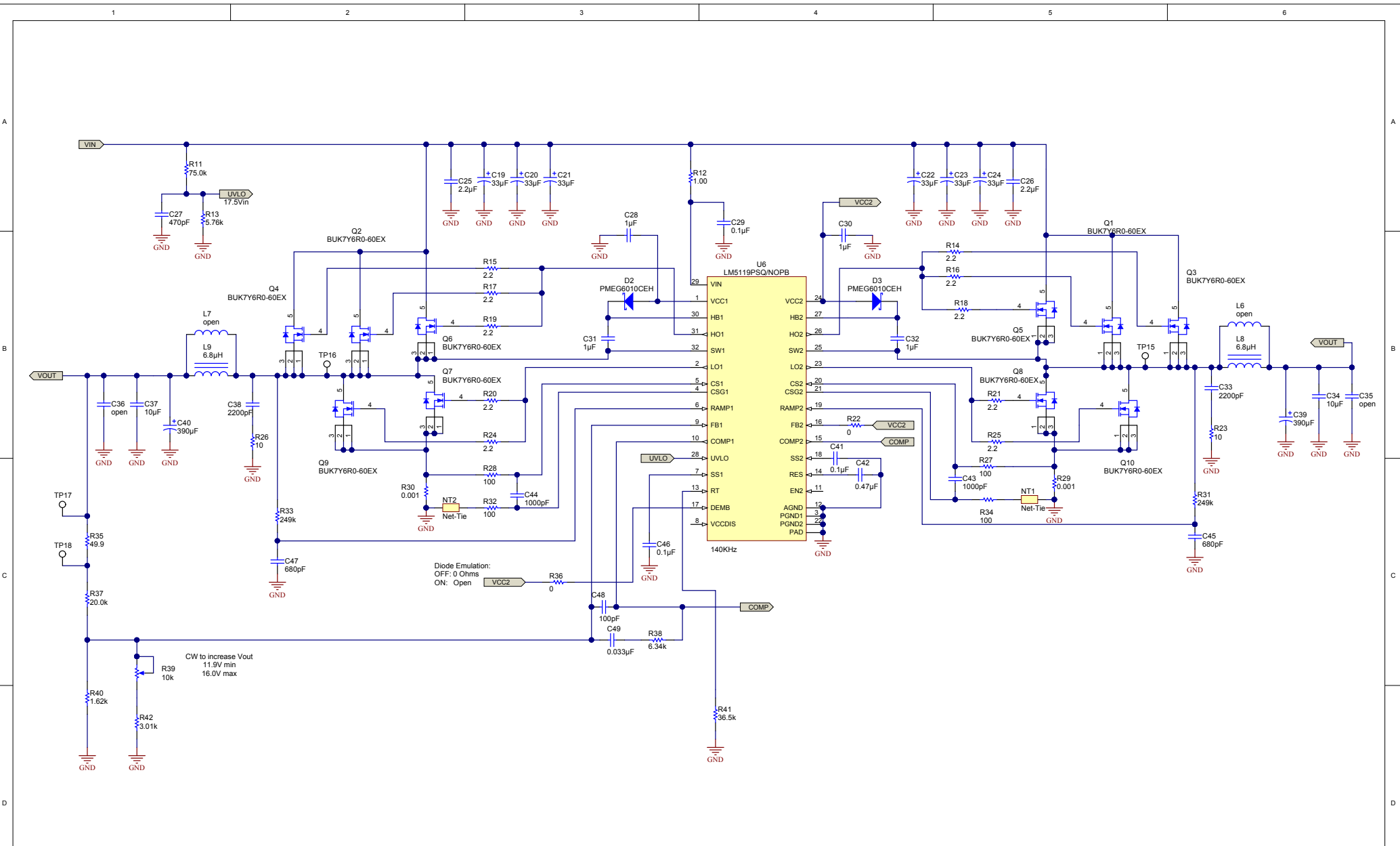


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Project Title: LM5119 4-Phase sync buck	
Number: PMP10260	Rev: B
SVN Rev: Version control disabled	Assembly Variant: 001
Drawn By: J Betten	File: PMP10260 REVB SH1.SchDoc
Engineer: J Betten	Contact: http://www.ti.com/support
	Sheet: 1 of 3
	Size: B

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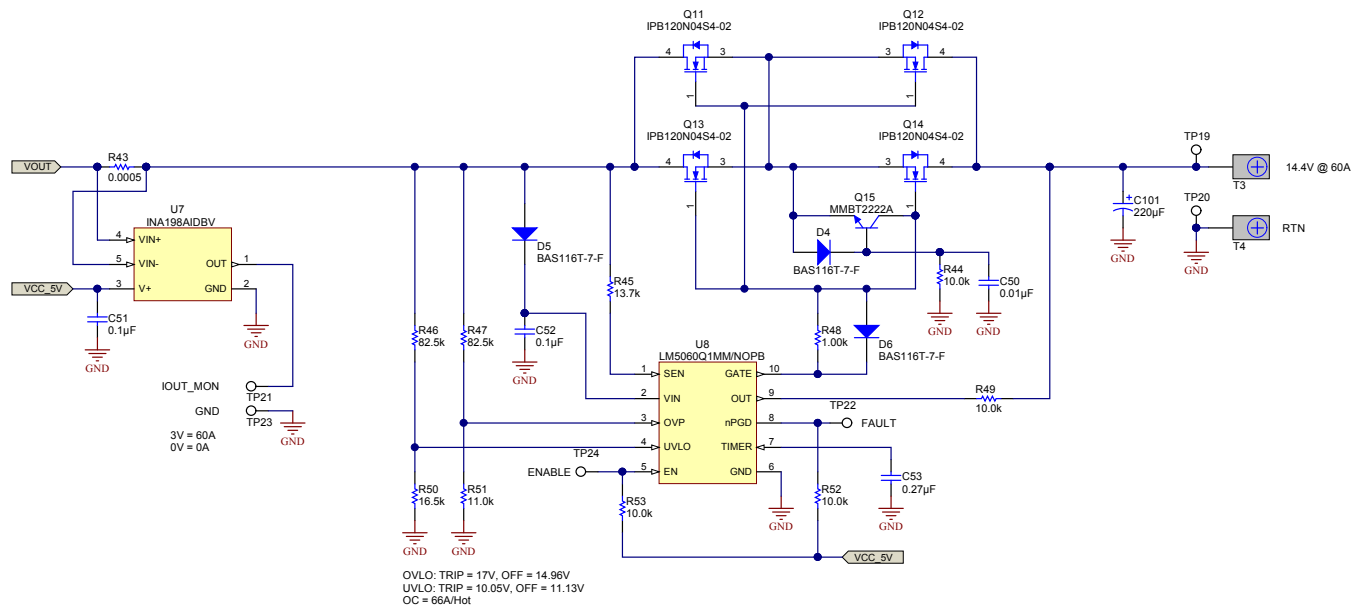


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Project Title: LM5119 4-Phase sync buck			
Number: PMP10260	Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3	
Drawn By:	File: PMP10260 REV B SH2 SchDoc	Size: B	
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Project Title: LM5119 4-Phase sync buck			
Number: PMP10260	Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:	File: PMP10260 REV B SH3.SchDoc	Size: B	
Engineer: J Betten	Contact: http://www.ti.com/support		

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